

Jacob Elias

List of Publications by Year in descending order

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Version: 2024-02-01

11
papers

65
citations

1937685

4
h-index

1588992

8
g-index

11
all docs

11
docs citations

11
times ranked

53
citing authors

#	ARTICLE	IF	CITATIONS
1	Cross-recurrence plot quantification analysis of input and output signals for the detection of chatter in turning. <i>Nonlinear Dynamics</i> , 2014, 76, 255-261.	5.2	29
2	Experimental Investigation on the Effect of Ag Addition on Ternary Lead Free Solder Alloy Sn-0.5Cu-3Bi . <i>Metals and Materials International</i> , 2020, 26, 107-114.	3.4	18
3	Experimental investigations on the effect of addition of Ag into ternary lead free solder alloy Sn-1Cu-1Ni. <i>Letters on Materials</i> , 2019, 9, 239-242.	0.7	8
4	Investigations on the properties of new lead free solder alloy composition Sn-0.5Cu-3.5Bi . <i>Materials Today: Proceedings</i> , 2020, 21, 329-331.	1.8	4
5	Investigations on the Corrosion Properties of Sn-0.5Cu-3Bi-xAg Lead Free Solder Alloys in 3.5% NaCl Solution. <i>Transactions on Electrical and Electronic Materials</i> , 2021, 22, 150-159.	1.9	2
6	Recurrence quantification analysis applied to sequential speckle images of machined surface for detection of chatter in turning. <i>Proceedings of SPIE</i> , 2008, , .	0.8	1
7	Experimental Investigations on Impact Toughness and Shear Strength of Lead Free Solder Alloy Sn-0.5Cu-3Bi-xAg . <i>Transactions on Electrical and Electronic Materials</i> , 2020, 21, 191-197.	1.9	1
8	Experimental and finite element analysis on determining the fatigue life of pb-free solder joint (Sn-0.5Cu-3Bi-1Ag) used in electronic packages under harmonic loads. <i>International Journal of Modeling, Simulation, and Scientific Computing</i> , 2020, 11, 2050020.	1.4	1
9	Investigations on the Corrosion Properties of Sn-1Cu-1Ni-xAg Lead Free Solders in 3.5% NaCl Solution. <i>Protection of Metals and Physical Chemistry of Surfaces</i> , 2021, 57, 858-865.	1.1	1
10	Factorial design and design of experiments for developing novel lead free solder alloy with Sn, Cu and Ni. <i>International Journal for Simulation and Multidisciplinary Design Optimization</i> , 2020, 11, 18.	1.1	0
11	Experimental Investigations on Impact Toughness and Shear Strength of Novel Lead Free Solder Alloy Sn-1Cu-1Ni-XAg. <i>Powder Metallurgy Progress</i> , 2019, 19, 90-96.	0.1	0